

Leveraging our innovative and patented Enhanced Spray Technology™, Cintillio™ Spray Solvent Tool offers wet-chemical processing to meet most any application demand. SST processes multiple wafer sizes with one carrier change. And with the smallest footprint (12 feet²) among similar equipment, Cintillio Spray Solvent Tool not only saves fab-floor real estate, it also enables high up-time and low cost of ownership.



● Features and Benefits:

- 25- and 50-wafer batch process—High throughput, semi-automated
- Reduced drag out together with reduced chemical and DI water consumption mean low cost of ownership
- Flexible chemical configurations: Up to 4 chemical tanks
 - Modular construction and service-friendly design
 - Components are universal across Cintillio platforms
 - Mechanical and centrifugal forces on wafers rotating in a closed chamber assist and enhance the reaction of chemicals on the wafer surface
 - Closed-loop process control for statistical consistency
 - Continuously recycled and filtered chemicals
 - Minimal exhaust requirements
 - Chemical reclaiming capability minimizes chemical use



Single- and dual-chamber Spray Solvent Tool

● Key Capabilities

- Fast install and start-up time
- High up time
- High MTBF
- Low maintenance
- Low spare-part costs

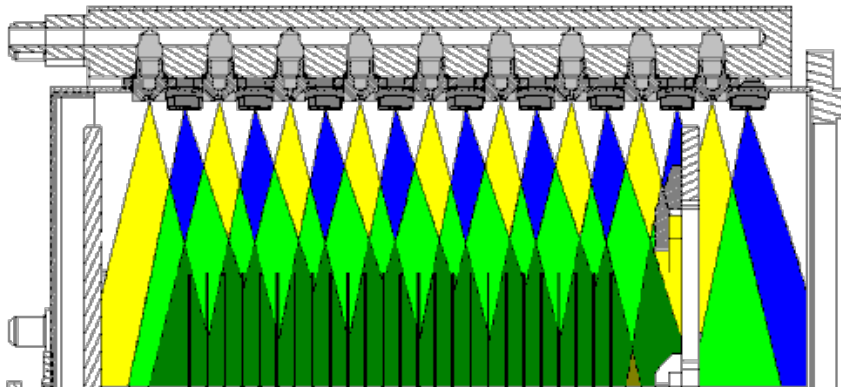
● Applications

- Poly etch clean, polymer removal BEOL
- Resist developing, positive or negative photo-resist strip
- Substrate and mask cleaning
- Metal lift off, flux removal

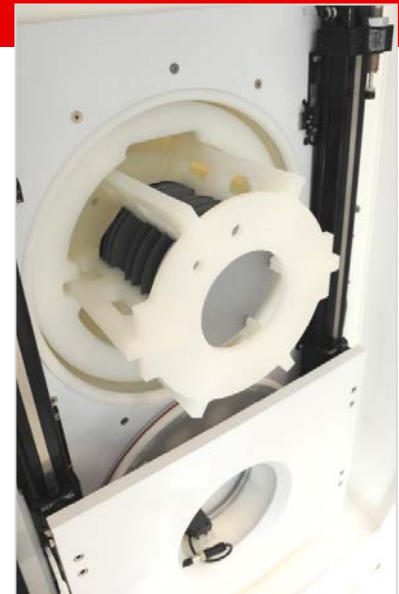


Cintillio™ tools are part of OEM Group's LEGENDS™ family of systems

Enhanced Spray Technology



Enhanced Spray Technology™ offers uniform media flow across the wafers and efficient media extraction from the process chamber. Efficient rinsing means higher yield.



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